
San Jose, California, USA
13-17 March 2017
SESSION 1: Auto/Aerospace/Outdoor Applications

Chair: Josh Gess, Oregon State University

1. Design of Thermal System Based on Combination of Thermoelectric and Vapor Chamber Technologies
   - Alex Gurevich, Isaac Steiner, Eric Huang
   - 1 Double Check Ltd, Israel; 2 Leading Edge Associated Co., LTD, Japan
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2. Study of an Innovative Multiple Fans System with one Piezoelectric Actuator Embedded in a Circular Heat Sink
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3. Development of a Passively Cooled Outdoor Telecom Power Enclosure
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   - 1 Simon Fraser University, Canada; 2 Alpha Technologies Ltd., Canada
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4. Thermal Analysis of Hybrid Circuits with Variable Heat Transfer Coefficient
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   - Robin Bornoff, Mentor Graphics, UK; Andras Vass-Varnai, Mentor Graphics, South Korea; Byron Blackmore, Mentor Graphics, Canada; Gang Wang, Mentor Graphics, China; Voon Hon Wong, Mentor Graphics, Singapore
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